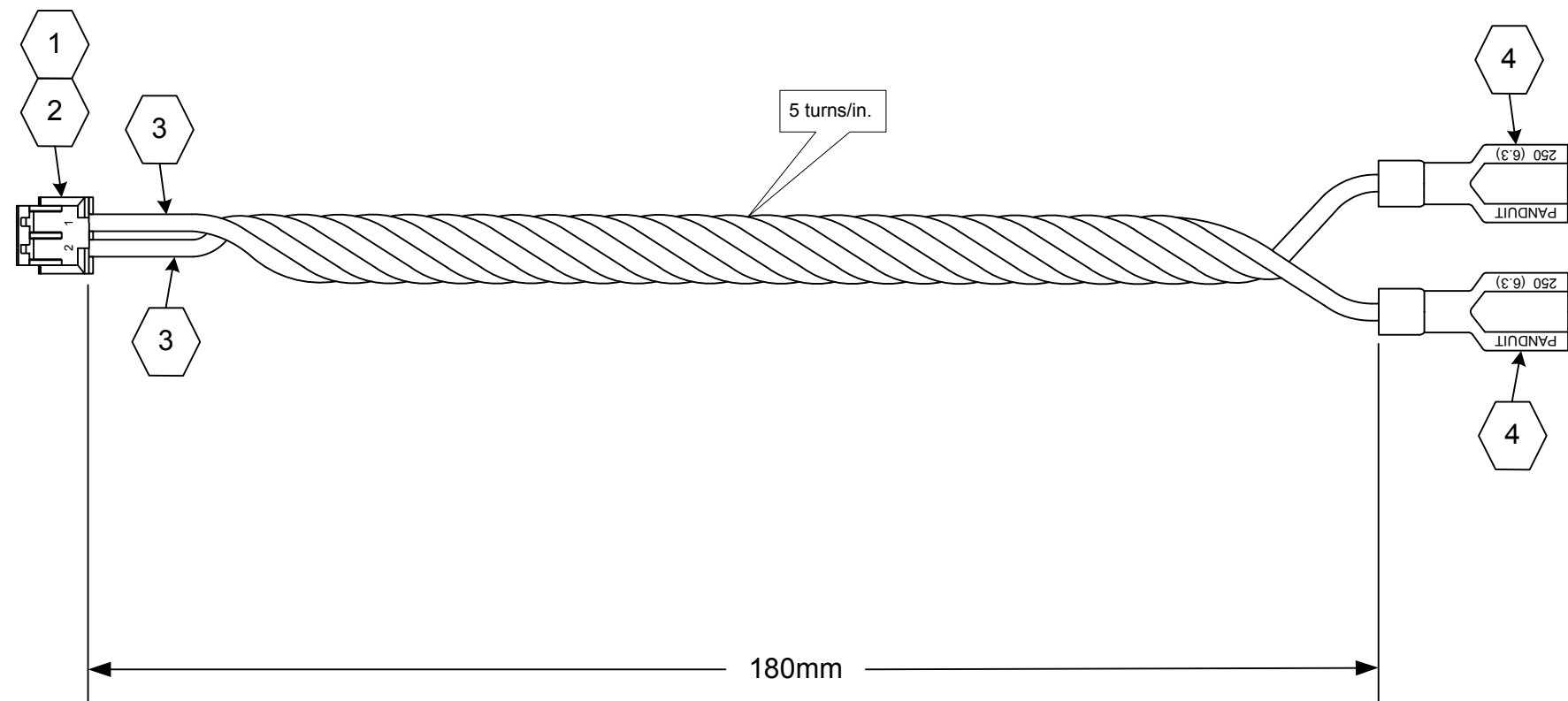


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<table><tr><td></td><td></td><td>OWN</td><td>P Cleveland</td><td>DATE</td><td>01/29/2014</td><td colspan="4" rowspan="3">TEXAS INSTRUMENTS © COPYRIGHT 2014 TEXAS INSTRUMENTS ALL RIGHTS RESERVED</td></tr><tr><td></td><td></td><td>ENGR</td><td>Eric Pruett</td><td></td><td>01/29/2014</td></tr><tr><td></td><td></td><td>APVD</td><td>Joe Siddall</td><td></td><td>01/29/2014</td></tr><tr><td></td><td></td><td>MFG</td><td></td><td></td><td></td><td colspan="4" rowspan="2">NIRscan, Lamp Driver Cable</td></tr><tr><td></td><td></td><td>GA</td><td></td><td></td><td></td></tr><tr><td></td><td>314 CP</td><td></td><td></td><td></td><td></td><td colspan="4"></td></tr><tr><td>NEXT ASSY</td><td>USED ON</td><td></td><td></td><td></td><td></td><td>B</td><td>DRAWING NO</td><td>2513486</td><td>REV</td><td>A</td></tr><tr><td colspan="2">APPLICATION</td><td>SW</td><td colspan="3">Microsoft® Office® Visio® 2007</td><td colspan="2">SCALE</td><td>NONE</td><td>SHEET</td><td>1 of 3</td></tr></table>												OWN	P Cleveland	DATE	01/29/2014	TEXAS INSTRUMENTS © COPYRIGHT 2014 TEXAS INSTRUMENTS ALL RIGHTS RESERVED						ENGR	Eric Pruett		01/29/2014			APVD	Joe Siddall		01/29/2014			MFG				NIRscan, Lamp Driver Cable						GA					314 CP									NEXT ASSY	USED ON					B	DRAWING NO	2513486	REV	A	APPLICATION		SW	Microsoft® Office® Visio® 2007			SCALE		NONE	SHEET	1 of 3
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Quantity	Item	Part Number	Description	Manuf.
1	1	EHR-2	EH 2 Pin 2.5mm Connector Housing	JST
2	2	SEH-001T-P0.6	EH 22-30 AWG Crimp Pin	JST
2	3	1855/19 BK	Black 22 AWG PVC hook-up wire	Alpha
2	4	DNF18-250FIB-C	Fully Insulated Female Disconnect	Panduit

- NOTE:
- Wire may be substituted with wire that meets or exceeds the published specification of the wire listed.
 - Wire color choice is optional.

NIRscan Lamp Cable

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Revision History															
A		ECO# 2136371, Initial Release													

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